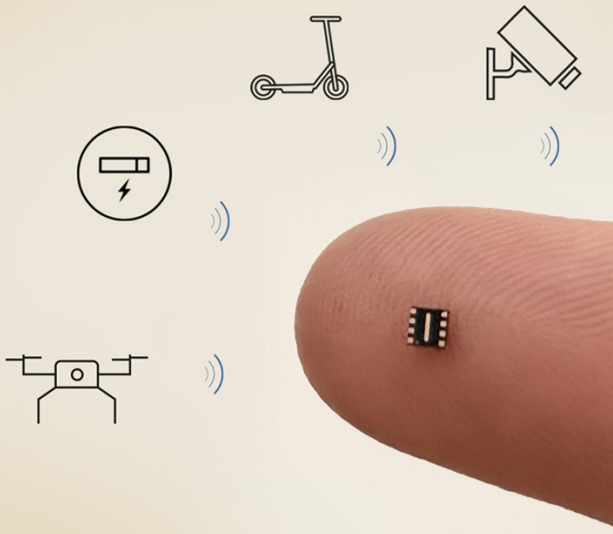
WORKZ

IoT module range



Workz overview

- Over 25 years' experience providing SIM solutions
- 150+ telcos in 80+ countries
- GSMA SAS-UP certified facility for SIM and embedded modules production
- The global leader in cloud-based eSIM solutions
- Hailed as the most complete and innovative eSIM solution
- Personalised service dedicated to telcos

Workz supplies telcos and OEMs with IoT eSIM modules in various form factors, grades, life span, capacities, O/S and add-ons (e.g. applets) as described in more detail below. For activation and remote management please see Workz offering for cloud eSIM and OTA PaaS solutions.

Forms

Removable

2FF, 3FF & 4FF
Size
25 x 15 x 0.76 mm

Embedded

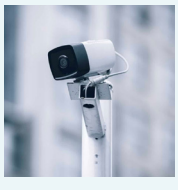
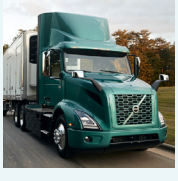
DFN8
Chip size
6 x 5 x 0.75 mm

VSON10
Chip size
3 x 3 x 0.5 mm

DFN6
Chip size
3 x 2.3 x 0.60 mm

USON8
Chip size
2 x 2 x 0.65 mm

Types

Use	 **Classic / Residential**	 **Industrial**	 **Automotive**
Devices	Indoor: alarms, CCTV, health, wearables	Vending machines, monitoring devices	Transport
Temp	-25°C to 85°C	-40°C to 105°C	-40°C to 105°C
Lifespan	25 years @ 25°C 100K read/write	15 years @ 85°C 500K read/write	17 years @ 105°C 1M read/write
Capacity	132KB - 1MB	256KB - 1MB	600KB - 2MB
Chip	Infineon SLC16ECB240B (UICC – 240kB) TMC THC80F228B (UICC – 228kB) TMC THC80F340A (UICC – 340kB) Huada CIU98228H (UICC – 228kB) Samsung S3FW9FV (UICC – 420kB)	Samsung S3FW9FJM (UICC/eUICC – 702kB) Infineon SLM17ECB800B (UICC/eUICC – 800kB) * Silver-free module available	Available upon request

Compliance

Chip	Common Criteria	✓ EAL ; PP-35/0084
OS	GSMA	✓ SGP.11 RSP v3.1; SGP.14 eUICC PKI v1.1; ✓ SGP.02 v3.2 ; SGP.05 eUICC PP-0089
	simalliance	✓ eUICC Profile Package v2.1
	GLOBALPLATFORM	✓ Product Qualification
Production	GSMA Security Accreditation Scheme	✓ SAS-UP eUICC ; EUM
Remote SIM provisioning	GSMA	✓ SGP.01 RSP v1.1 ; SGP.11 RSP v3.2 & 3.1 ; ✓ SGP.14 eUICC PKI v1.1 ; SAS-SM

Pin functions

DFN8

DFN6

USON

- Ground
- Input/output (serial data)
- Clock (external clock input)
- Reset (system reset input)
- Power input
- Not connected

MFF2 packing

Bags are vacuum-sealed and include drying desiccant bags and humidity indicator

Reels are packed in anti-static, moisture-barrier bags (MSL 1)

Data labels on module reel,bag, inner boxes, and master cartons

Technical services

- ✓ Advanced eUICC or UICC SIM OS
- ✓ Profile development & testing
- ✓ GSMA SAS-certified data preparation
- ✓ Optional cloud-based subscription services

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